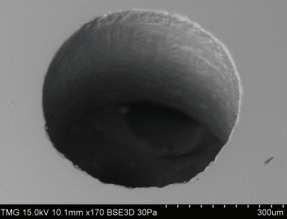


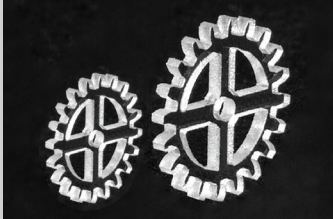
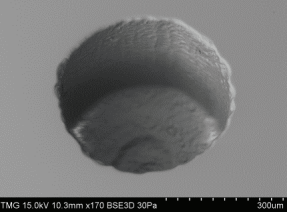

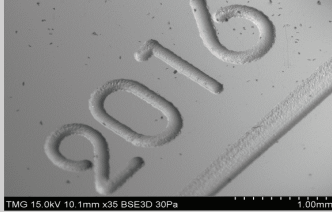
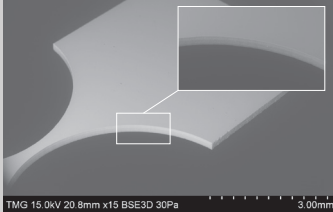


## YOUR JOB SHOP SOLUTION FOR GLASS MICRO-MACHINING

### MACHINING OPERATIONS

	DRILLING	MILLING	ENGRAVING	CUTTING
THROUGH	 TMG 15.0kV 10.1mm x170 BSE3D 30Pa 300µm			
BLIND	 TMG 15.0kV 10.3mm x170 BSE3D 30Pa 300µm	 TMG 15.0kV 10.3mm x45 BSE3D 30Pa 1.00mm	 TMG 15.0kV 10.1mm x95 BSE3D 30Pa 1.00mm	 TMG 15.0kV 20.8mm x15 BSE3D 30Pa 3.00mm
	AND TAPERED HOLES			

Stress less / micro-crack free / no burrs and particles

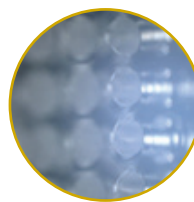
High precision micro-machining of all types of glass and materials with silicon dioxide



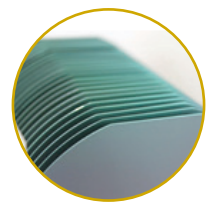
GLASS  
Pyrex, BF33, D263T,  
Mempax, AF32, B270,  
...



TEMPERED GLASS  
Corning Gorilla, AGC Dragontrail,  
Schott Xensation, ...



QUARTZ  
Fused silica



SILICON

and more...

### SPECIFICATIONS

- Width machining > 60 µm
- Ratio: 1:10
- Thickness: 30 µm up to 4 mm
- Roughness: Ra > 0.4 µm
- Machining area: 220 x 220 mm
- Chipping: <10 µm



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